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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	15000
Total RAM Bits	331776
Number of I/O	188
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp15e-4fn256c

Features

■ Non-volatile, Infinitely Reconfigurable

- Instant-on – powers up in microseconds
- No external configuration memory
- Excellent design security, no bit stream to intercept
- Reconfigure SRAM based logic in milliseconds
- SRAM and non-volatile memory programmable through system configuration and JTAG ports

■ Sleep Mode

- Allows up to 1000x static current reduction

■ TransFR™ Reconfiguration (TFR)

- In-field logic update while system operates

■ Extensive Density and Package Options

- 3.1K to 19.7K LUT4s
- 62 to 340 I/Os
- Density migration supported

■ Embedded and Distributed Memory

- 54 Kbits to 396 Kbits sysMEM™ Embedded Block RAM
- Up to 79 Kbits distributed RAM
- Flexible memory resources:
 - Distributed and block memory

■ Flexible I/O Buffer

- Programmable sysIO™ buffer supports wide range of interfaces:
 - LVCMOS 3.3/2.5/1.8/1.5/1.2
 - LVTTTL
 - SSTL 18 Class I
 - SSTL 3/2 Class I, II
 - HSTL15 Class I, III
 - HSTL 18 Class I, II, III
 - PCI
 - LVDS, Bus-LVDS, LVPECL, RSDS

■ Dedicated DDR Memory Support

- Implements interface up to DDR333 (166MHz)

■ sysCLOCK™ PLLs

- Up to 4 analog PLLs per device
- Clock multiply, divide and phase shifting

■ System Level Support

- IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
- Onboard oscillator for configuration
- Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply

Table 1-1. LatticeXP Family Selection Guide

Device	LFXP3	LFXP6	LFXP10	LFXP15	LFXP20
PFU/PFF Rows	16	24	32	40	44
PFU/PFF Columns	24	30	38	48	56
PFU/PFF (Total)	384	720	1216	1932	2464
LUTs (K)	3	6	10	15	20
Distributed RAM (KBits)	12	23	39	61	79
EBR SRAM (KBits)	54	72	216	324	396
EBR SRAM Blocks	6	8	24	36	44
V _{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
PLLs	2	2	4	4	4
Max. I/O	136	188	244	300	340
Packages and I/O Combinations:					
100-pin TQFP (14 x 14 mm)	62				
144-pin TQFP (20 x 20 mm)	100	100			
208-pin PQFP (28 x 28 mm)	136	142			
256-ball fpBGA (17 x 17 mm)		188	188	188	188
388-ball fpBGA (23 x 23 mm)			244	268	268
484-ball fpBGA (23 x 23 mm)				300	340

Architecture Overview

The LatticeXP architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR) as shown in Figure 2-1.

On the left and right sides of the PFU array, there are Non-volatile Memory Blocks. In configuration mode this non-volatile memory is programmed via the IEEE 1149.1 TAP port or the sysCONFIG™ peripheral port. On power up, the configuration data is transferred from the Non-volatile Memory Blocks to the configuration SRAM. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. This transfer of data from non-volatile memory to configuration SRAM via wide busses happens in microseconds, providing an “instant-on” capability that allows easy interfacing in many applications.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional unit without RAM/ROM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM and register functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row. The PFU blocks are used on the outside rows. The rest of the core consists of rows of PFF blocks interspersed with rows of PFU blocks. For every three rows of PFF blocks there is a row of PFU blocks.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysIO interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM or ROM.

The PFU, PFF, PIC and EBR Blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

At the end of the rows containing the sysMEM Blocks are the sysCLOCK Phase Locked Loop (PLL) Blocks. These PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeXP architecture provides up to four PLLs per device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG port which allows for serial or parallel device configuration. The LatticeXP devices are available for operation from 3.3V, 2.5V, 1.8V and 1.2V power supplies, providing easy integration into the overall system.

Table 2-1. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCIN	Fast Carry In ¹
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8 ² MUX depending on the slice
Output	Inter-PFU signal	FCO	For the right most PFU the fast carry chain output ¹

1. See Figure 2-2 for connection details.

2. Requires two PFUs.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

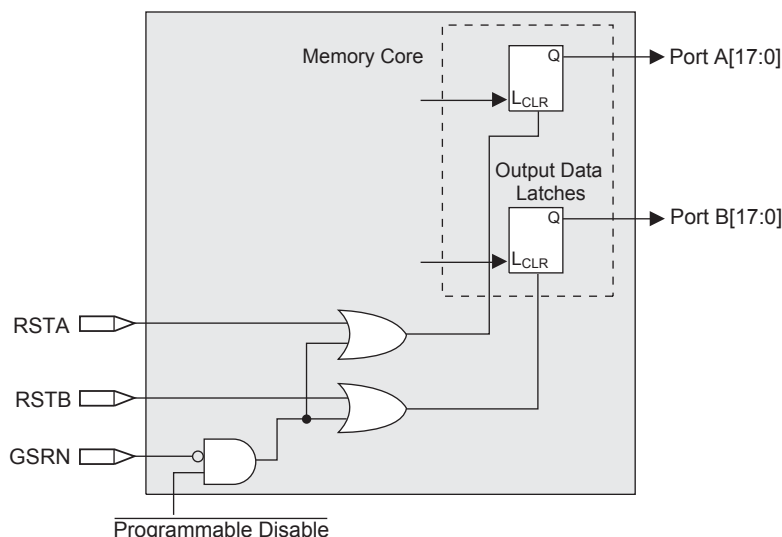
Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
 - A greater-than-or-equal-to B
 - A not-equal-to B
 - A less-than-or-equal-to B

Two additional signals: Carry Generate and Carry Propagate are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

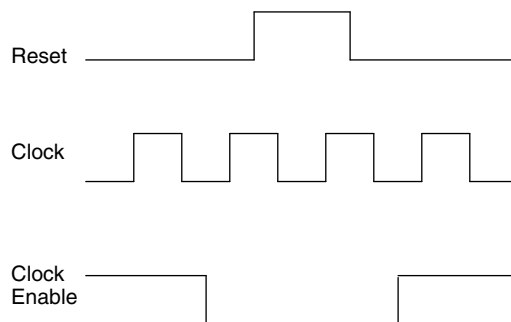
RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

Figure 2-15. Memory Core Reset

For further information on sysMEM EBR block, see the details of additional technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-16. The GSR input to the EBR is always asynchronous.

Figure 2-16. EBR Asynchronous Reset (Including GSR) Timing Diagram

If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

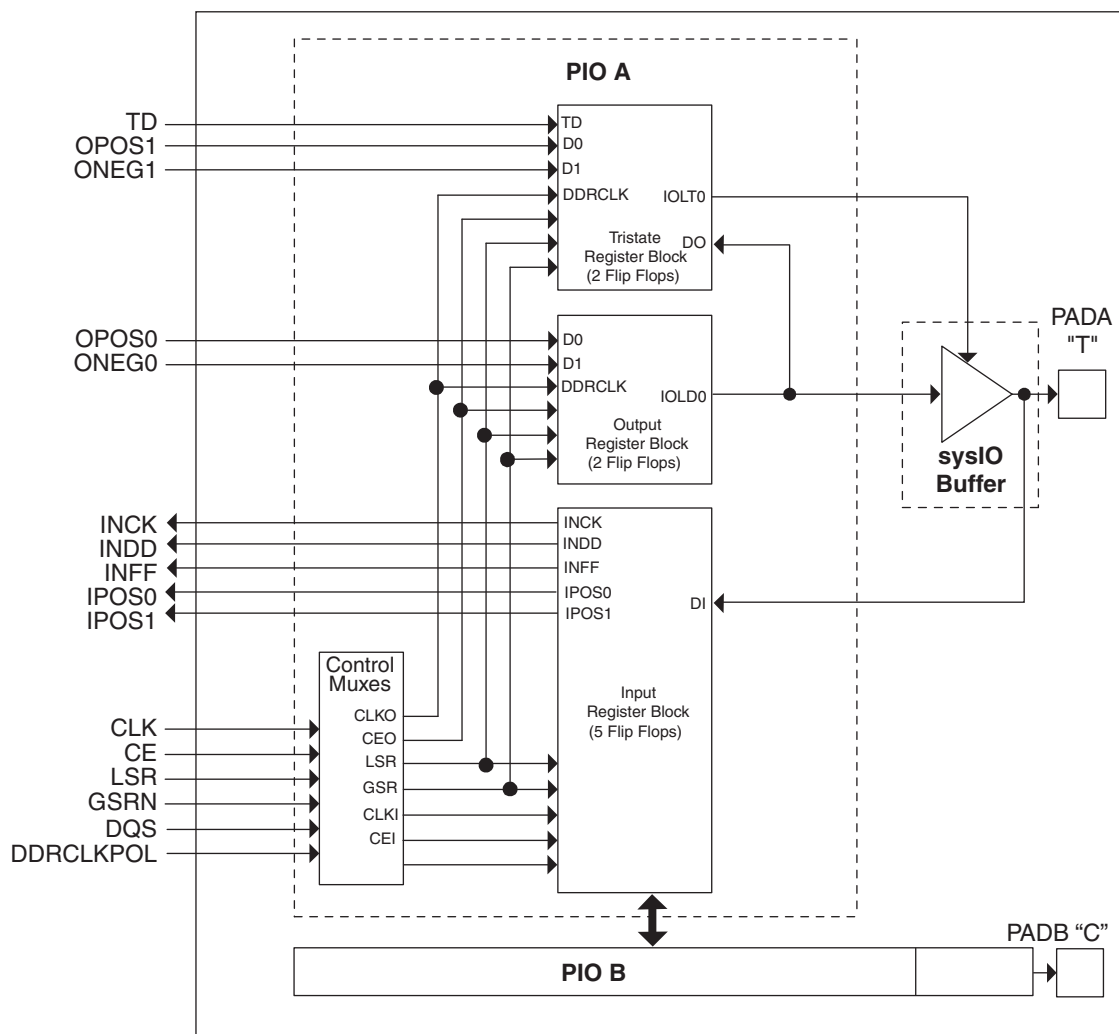
These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

Programmable I/O Cells (PICs)

Each PIC contains two PIOs connected to their respective sysIO Buffers which are then connected to the PADs as shown in Figure 2-17. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to sysIO buffer, and receives input from the buffer.

Figure 2-17. PIC Diagram



In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

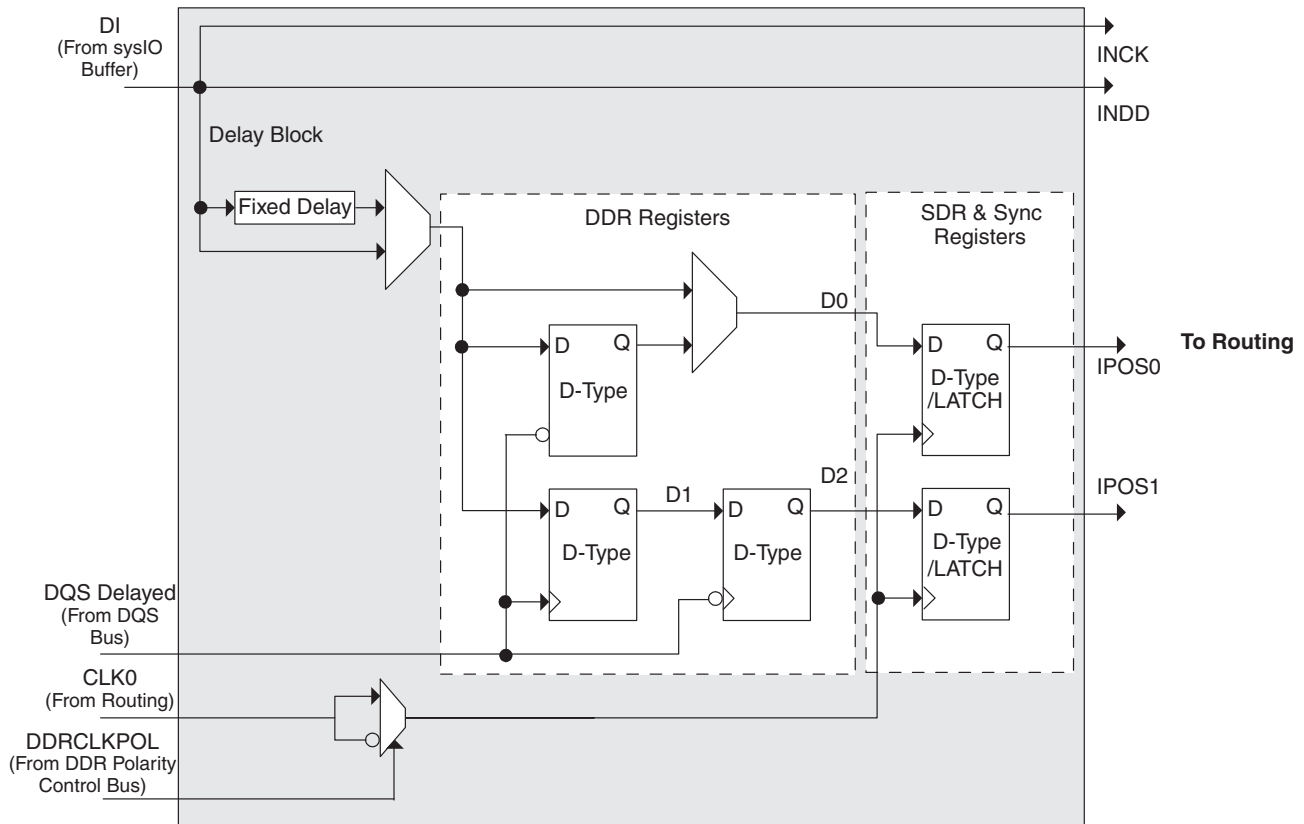
in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, ensures no positive input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-21 shows the input register waveforms for DDR operation and Figure 2-22 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to the system clock domain. For further discussion of this topic, see the DDR memory section of this data sheet.

Figure 2-20. Input Register Diagram



Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to V_{CCIO} . The I/O pins will not take on the user configuration until V_{CC} , V_{CCAUX} and V_{CCIO} have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported Standards

The LatticeXP sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5 and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, BLVDS, LVPECL, differential SSTL and differential HSTL. Tables 2-7 and 2-8 show the I/O standards (together with their supply and reference voltages) supported by the LatticeXP devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Table 2-7. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}^1 (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33 ²	—	—
LVCMOS25 ²	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12 ²	—	—
PCI	—	3.3
HSTL18 Class I, II	0.9	—
HSTL18 Class III	1.08	—
HSTL15 Class I	0.75	—
HSTL15 Class III	0.9	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I	0.9	—
Differential Interfaces		
Differential SSTL18 Class I	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I, III	—	—
Differential HSTL18 Class I, II, III	—	—
LVDS, LVPECL	—	—
BLVDS	—	—

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.

2. JTAG inputs do not have a fixed threshold option and always follow V_{CCJ} .

Figure 2-29 provides a pictorial representation of the different programming ports and modes available in the LatticeXP devices.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port.

Leave Alone I/O

When using 1532 mode for non-volatile memory programming, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

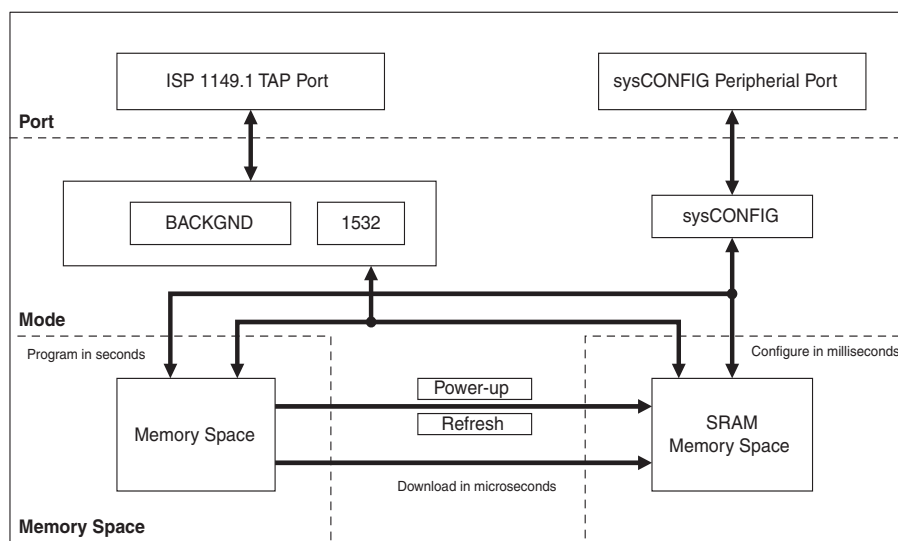
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See Lattice technical note #TN1087, *Minimizing System Interruption During Configuration Using TransFR Technology*, for details.

Security

The LatticeXP devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-29. ispXP Block Diagram



Internal Logic Analyzer Capability (ispTRACY)

All LatticeXP devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information on ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

Oscillator

Every LatticeXP device has an internal CMOS oscillator which is used to derive a master serial clock for configuration. The oscillator and the master serial clock run continuously in the configuration mode. The default value of the

Derating Logic Timing

Logic timing provided in the following sections of this data sheet and in the ispLEVER design tools are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best-case process can be much better than the values given in the tables. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

LatticeXP Family Timing Adders¹ (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.8	0.8	0.8	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.5	0.5	0.5	ns
LVTTTL33_12mA	LVTTTL 12mA drive	0.3	0.3	0.3	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.4	0.4	0.4	ns
LVTTTL33_20mA	LVTTTL 20mA drive	0.3	0.3	0.3	ns
LVC MOS33_2mA	LVC MOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVC MOS25_2mA	LVC MOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVC MOS18_2mA	LVC MOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVC MOS15_2mA	LVC MOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVC MOS 2.5, 12mA.
Timing v.F0.11

Flash Download Time

Symbol	Parameter		Min.	Typ.	Max.	Units
t _{REFRESH}	PROGRAMN Low-to-High. Transition to Done High.	LFXP3	—	1.1	1.7	ms
		LFXP6	—	1.4	2.0	ms
		LFXP10	—	0.9	1.5	ms
		LFXP15	—	1.1	1.7	ms
		LFXP20	—	1.3	1.9	ms

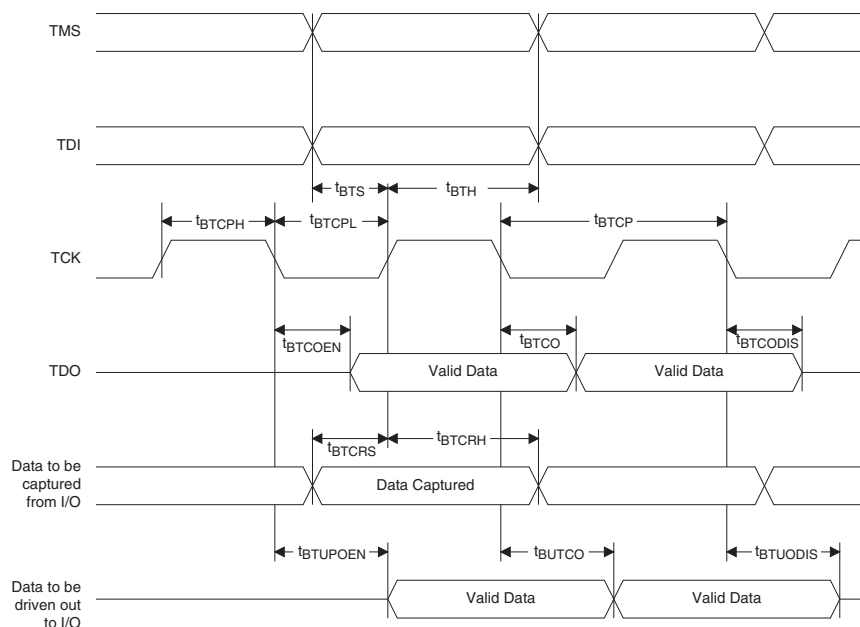
JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
f_{MAX}		—	25	MHz
t_{BTCP}	TCK [BSCAN] clock pulse width	40	—	ns
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	10	—	ns
t_{BTH}	TCK [BSCAN] hold time	8	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
t_{BTCODIS}	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	25	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
t_{BTUODIS}	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
t_{BTUPOEN}	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

Timing v.F0.11

Figure 3-12. JTAG Port Timing Waveforms



Pin Information Summary¹

Pin Type		XP3			XP6		
		100 TQFP	144 TQFP	208 PQFP	144 TQFP	208 PQFP	256 fpBGA
Single Ended User I/O		62	100	136	100	142	188
Differential Pair User I/O ²		19	35	56	35	58	80
Configuration	Dedicated	11	11	11	11	11	11
	Muxed	14	14	14	14	14	14
TAP		5	5	5	5	5	5
Dedicated (total without supplies)		6	6	6	6	6	6
V _{CC}		2	4	8	4	8	8
V _{CCAUX}		2	2	2	2	2	4
V _{CCPLL}		2	2	2	2	2	2
V _{CCIO}	Bank0	1	1	2	1	2	2
	Bank1	1	1	2	1	2	2
	Bank2	1	1	2	1	2	2
	Bank3	1	1	2	1	2	2
	Bank4	1	2	2	2	2	2
	Bank5	1	1	2	1	2	2
	Bank6	1	1	2	1	2	2
	Bank7	1	1	2	1	2	2
GND		10	13	24	13	24	24
GND _{PLL}		2	2	2	2	2	2
NC		0	0	6	0	0	0
Single Ended/Differential I/O per Bank ²	Bank0	8/2	12/3	20/8	12/3	20/8	26/11
	Bank1	9/0	12/2	18/6	12/2	18/6	26/11
	Bank2	8/3	12/5	14/6	12/5	17/7	21/9
	Bank3	6/2	13/5	14/6	13/5	14/6	21/9
	Bank4	5/2	14/6	21/9	14/6	21/9	26/11
	Bank5	12/4	12/4	21/9	12/4	21/9	26/11
	Bank6	4/2	13/5	14/6	13/5	17/7	21/9
	Bank7	10/4	12/5	14/6	12/5	14/6	21/9
V _{CCJ}		1	1	1	1	1	1

1. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.

2. The differential I/O per bank includes both dedicated LVDS and emulated LVDS pin pairs. Please see the Logic Signal Connections table for more information.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
47	PB11A	5	T	DQS	PB14A	5	T	DQS
48	PB11B	5	C	-	PB14B	5	C	-
49	VCCIO5	5	-	-	VCCIO5	5	-	-
50	PB12A	5	T	-	PB15A	5	T	-
51	PB12B	5	C	-	PB15B	5	C	-
52	PB13A	5	T	-	PB16A	5	T	-
53	PB13B	5	C	-	PB16B	5	C	-
54	GND	-	-	-	GND	-	-	-
55	PB14A	4	T	-	PB17A	4	T	-
56	GNDIO4	4	-	-	GNDIO4	4	-	-
57	PB14B	4	C	-	PB17B	4	C	-
58	PB15A	4	T	PCLKT4_0	PB18A	4	T	PCLKT4_0
59	PB15B	4	C	PCLKC4_0	PB18B	4	C	PCLKC4_0
60	PB16A	4	T	-	PB19A	4	T	-
61	VCCIO4	4	-	-	VCCIO4	4	-	-
62	PB16B	4	C	-	PB19B	4	C	-
63	PB19A	4	T	DQS	PB22A	4	T	DQS
64	GNDIO4	4	-	-	GNDIO4	4	-	-
65	PB19B	4	C	VREF1_4	PB22B	4	C	VREF1_4
66	PB20A	4	T	-	PB23A	4	T	-
67	PB20B	4	C	-	PB23B	4	C	-
68	VCCIO4	4	-	-	VCCIO4	4	-	-
69	PB22A	4	-	-	PB25A	4	-	-
70	PB24A	4	T	VREF2_4	PB27A	4	T	VREF2_4
71	PB24B	4	C	-	PB27B	4	C	-
72	PB25A	4	-	-	PB28A	4	-	-
73	VCC	-	-	-	VCC	-	-	-
74	PR18B	3	C ³	-	PR26B	3	C ³	-
75	GNDIO3	3	-	-	GNDIO3	3	-	-
76	PR18A	3	T ³	-	PR26A	3	T ³	-
77	PR17B	3	C	-	PR25B	3	C	-
78	PR17A	3	T	-	PR25A	3	T	-
79	PR16B	3	C ³	-	PR24B	3	C ³	-
80	PR16A	3	T ³	DQS	PR24A	3	T ³	DQS
81	PR15B	3	-	VREF1_3	PR23B	3	-	VREF1_3
82	PR14A	3	-	VREF2_3	PR22A	3	-	VREF2_3
83	PR13B	3	C	-	PR21B	3	C ³	-
84	PR13A	3	T	-	PR21A	3	T ³	-
85	GND	-	-	-	GND	-	-	-
86	PR12A	3	-	-	PR20A	3	-	-
87	PR11B	3	C	-	PR19B	3	C ³	-
88	VCCIO3	3	-	-	VCCIO3	3	-	-
89	PR11A	3	T	-	PR19A	3	T ³	-
90	GNDP1	-	-	-	GNDP1	-	-	-
91	VCCP1	-	-	-	VCCP1	-	-	-
92	PR9B	2	C	PCLKC2_0	PR12B	2	C	PCLKC2_0

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
93	PB19B	4	C	VREF1_4	PB22B	4	C	VREF1_4
94	PB20A	4	T	-	PB23A	4	T	-
95	PB20B	4	C	-	PB23B	4	C	-
96	PB21A	4	T	-	PB24A	4	T	-
97	VCCIO4	4	-	-	VCCIO4	4	-	-
98	PB21B	4	C	-	PB24B	4	C	-
99	PB22A	4	T	-	PB25A	4	T	-
100	PB22B	4	C	-	PB25B	4	C	-
101	PB23A	4	T	-	PB26A	4	T	-
102	PB23B	4	C	-	PB26B	4	C	-
103	PB24A	4	T	VREF2_4	PB27A	4	-	VREF2_4
104	PB24B	4	C	-	PB30A	4	T	DQS
105	PB25A	4	-	-	PB30B	4	C	-
106	GND	-	-	-	GND	-	-	-
107	VCC	-	-	-	VCC	-	-	-
108	PR18B	3	C ³	-	PR26B	3	C ³	-
109	GNDIO3	3	-	-	GNDIO3	3	-	-
110	PR18A	3	T ³	-	PR26A	3	T ³	-
111	PR17B	3	C	-	PR25B	3	C	-
112	PR17A	3	T	-	PR25A	3	T	-
113	PR16B	3	C ³	-	PR24B	3	C ³	-
114	PR16A	3	T ³	DQS	PR24A	3	T ³	DQS
115	VCCIO3	3	-	-	VCCIO3	3	-	-
116	PR15B	3	-	VREF1_3	PR23B	3	-	VREF1_3
117	PR14A	3	-	VREF2_3	PR22A	3	-	VREF2_3
118	GNDIO3	3	-	-	GNDIO3	3	-	-
119	PR13B	3	C	-	PR21B	3	C ³	-
120	PR13A	3	T	-	PR21A	3	T ³	-
121	GND	-	-	-	GND	-	-	-
122	PR12B	3	C	-	PR20B	3	C	-
123	PR12A	3	T	-	PR20A	3	T	-
124	PR11B	3	C	-	PR19B	3	C ³	-
125	VCCIO3	3	-	-	VCCIO3	3	-	-
126	PR11A	3	T	-	PR19A	3	T ³	-
127	GNDP1	-	-	-	GNDP1	-	-	-
128	VCCP1	-	-	-	VCCP1	-	-	-
129	NC	-	-	-	PR13A	2	-	-
130	GND	-	-	-	GND	-	-	-
131	PR9B	2	C	PCLKC2_0	PR12B	2	C	PCLKC2_0
132	PR9A	2	T	PCLKT2_0	PR12A	2	T	PCLKT2_0
133	NC	-	-	-	PR11B	2	C ³	-
134	NC	-	-	-	PR11A	2	T ³	-
135	GNDIO2	2	-	-	GNDIO2	2	-	-
136	PR8B	2	C	RUM0_PLLC_IN_A	PR8B	2	C	RUM0_PLLC_IN_A
137	PR8A	2	T	RUM0_PLLT_IN_A	PR8A	2	T	RUM0_PLLT_IN_A
138	PR7B	2	C ³	-	PR7B	2	C ³	-

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
185	PT13A	0	T	CS1N	PT16A	0	T	CS1N
186	PT12B	0	C	PCLKC0_0	PT15B	0	C	PCLKC0_0
187	PT12A	0	T	PCLKT0_0	PT15A	0	T	PCLKT0_0
188	PT11B	0	C	-	PT14B	0	C	-
189	VCCIO0	0	-	-	VCCIO0	0	-	-
190	PT11A	0	T	DQS	PT14A	0	T	DQS
191	PT10B	0	-	-	PT13B	0	-	-
192	PT9A	0	-	DOUT	PT12A	0	-	DOUT
193	PT8B	0	C	-	PT11B	0	C	-
194	GNDIO0	0	-	-	GNDIO0	0	-	-
195	PT8A	0	T	WRITEN	PT11A	0	T	WRITEN
196	PT7B	0	C	-	PT10B	0	C	-
197	PT7A	0	T	VREF1_0	PT10A	0	T	VREF1_0
198	PT6B	0	C	-	PT9B	0	C	-
199	VCCIO0	0	-	-	VCCIO0	0	-	-
200	PT6A	0	T	DI	PT9A	0	T	DI
201	PT5B	0	C	-	PT8B	0	C	-
202	PT5A	0	T	CSN	PT8A	0	T	CSN
203	PT4B	0	C	-	PT7B	0	C	-
204	PT4A	0	T	-	PT7A	0	T	-
205	PT3B	0	-	VREF2_0	PT6B	0	-	VREF2_0
206	PT2B	0	-	-	PT5B	0	-	-
207	GND	-	-	-	GND	-	-	-
208	CFG0	0	-	-	CFG0	0	-	-

1. Applies to LFXP "C" only.
2. Applies to LFXP "E" only.
3. Supports dedicated LVDS outputs.

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
R8	PB16A	5	T	-	PB20A	5	T	-
T9	PB16B	5	C	-	PB20B	5	C	-
R9	PB17A	4	T	-	PB21A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P9	PB17B	4	C	-	PB21B	4	C	-
T10	PB18A	4	T	PCLKT4_0	PB22A	4	T	PCLKT4_0
T11	PB18B	4	C	PCLKC4_0	PB22B	4	C	PCLKC4_0
R10	PB19A	4	T	-	PB23A	4	T	-
P10	PB19B	4	C	-	PB23B	4	C	-
N9	PB20A	4	-	-	PB24A	4	-	-
M9	PB21B	4	-	-	PB25B	4	-	-
R12	PB22A	4	T	DQS	PB26A	4	T	DQS
-	GNDIO4	4	-	-	GNDIO4	4	-	-
T12	PB22B	4	C	VREF1_4	PB26B	4	C	VREF1_4
P13	PB23A	4	T	-	PB27A	4	T	-
R13	PB23B	4	C	-	PB27B	4	C	-
M11	PB24A	4	T	-	PB28A	4	T	-
N11	PB24B	4	C	-	PB28B	4	C	-
N10	PB25A	4	T	-	PB29A	4	T	-
M10	PB25B	4	C	-	PB29B	4	C	-
T13	PB26A	4	T	-	PB30A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P14	PB26B	4	C	-	PB30B	4	C	-
R11	PB27A	4	T	VREF2_4	PB31A	4	T	VREF2_4
P12	PB27B	4	C	-	PB31B	4	C	-
T14	PB28A	4	-	-	PB32A	4	-	-
R14	PB29B	4	-	-	PB33B	4	-	-
P11	PB30A	4	T	DQS	PB34A	4	T	DQS
N12	PB30B	4	C	-	PB34B	4	C	-
T15	PB31A	4	T	-	PB35A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
R15	PB31B	4	C	-	PB35B	4	C	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P15	PR26B	3	C ³	-	PR34B	3	C	RLM0_PLLC_FB_A
N15	PR26A	3	T ³	-	PR34A	3	T	RLM0_PLLT_FB_A
P16	PR24B	3	C ³	-	PR33B	3	C ³	-
R16	PR24A	3	T ³	DQS	PR33A	3	T ³	DQS
M15	PR15B	3	-	-	PR32B	3	-	-
N14	PR23B	3	-	VREF1_3	PR31A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR25B	3	C	-	PR29B	3	C	-
L13	PR25A	3	T	-	PR29A	3	T	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
T7	PB23B	5	C	-	PB27B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
P8	PB24A	5	T	-	PB28A	5	T	-
T8	PB24B	5	C	-	PB28B	5	C	-
R8	PB25A	5	T	-	PB29A	5	T	-
T9	PB25B	5	C	-	PB29B	5	C	-
R9	PB26A	4	T	-	PB30A	4	T	-
P9	PB26B	4	C	-	PB30B	4	C	-
T10	PB27A	4	T	PCLKT4_0	PB31A	4	T	PCLKT4_0
T11	PB27B	4	C	PCLKC4_0	PB31B	4	C	PCLKC4_0
-	GNDIO4	4	-	-	GNDIO4	4	-	-
R10	PB28A	4	T	-	PB32A	4	T	-
P10	PB28B	4	C	-	PB32B	4	C	-
N9	PB29A	4	-	-	PB33A	4	-	-
M9	PB30B	4	-	-	PB34B	4	-	-
R12	PB31A	4	T	DQS	PB35A	4	T	DQS
T12	PB31B	4	C	VREF1_4	PB35B	4	C	VREF1_4
P13	PB32A	4	T	-	PB36A	4	T	-
R13	PB32B	4	C	-	PB36B	4	C	-
M11	PB33A	4	T	-	PB37A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
N11	PB33B	4	C	-	PB37B	4	C	-
N10	PB34A	4	T	-	PB38A	4	T	-
M10	PB34B	4	C	-	PB38B	4	C	-
T13	PB35A	4	T	-	PB39A	4	T	-
P14	PB35B	4	C	-	PB39B	4	C	-
R11	PB36A	4	T	VREF2_4	PB40A	4	T	VREF2_4
P12	PB36B	4	C	-	PB40B	4	C	-
T14	PB37A	4	-	-	PB41A	4	-	-
R14	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P11	PB39A	4	T	DQS	PB43A	4	T	DQS
N12	PB39B	4	C	-	PB43B	4	C	-
T15	PB40A	4	T	-	PB44A	4	T	-
R15	PB40B	4	C	-	PB44B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P15	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
N15	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
Y10	PB11B	5	C	-	PB16B	5	C	-	PB20B	5	C	-
AA7	PB12A	5	T	-	PB17A	5	T	-	PB21A	5	T	-
AB7	PB12B	5	C	VREF2_5	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
Y7	PB13A	5	T	-	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA8	PB13B	5	C	-	PB18B	5	C	-	PB22B	5	C	-
AB8	PB14A	5	T	-	PB19A	5	T	-	PB23A	5	T	-
Y8	PB14B	5	C	-	PB19B	5	C	-	PB23B	5	C	-
AB9	PB15A	5	T	-	PB20A	5	T	-	PB24A	5	T	-
AA9	PB15B	5	C	-	PB20B	5	C	-	PB24B	5	C	-
W10	PB16A	5	-	-	PB21A	5	-	-	PB25A	5	-	-
W11	PB17B	5	-	-	PB22B	5	-	-	PB26B	5	-	-
AB10	PB18A	5	T	DQS	PB23A	5	T	DQS	PB27A	5	T	DQS
AA10	PB18B	5	C	-	PB23B	5	C	-	PB27B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA11	PB19A	5	T	-	PB24A	5	T	-	PB28A	5	T	-
AB11	PB19B	5	C	-	PB24B	5	C	-	PB28B	5	C	-
Y11	PB20A	5	T	-	PB25A	5	T	-	PB29A	5	T	-
Y12	PB20B	5	C	-	PB25B	5	C	-	PB29B	5	C	-
AB12	PB21A	4	T	-	PB26A	4	T	-	PB30A	4	T	-
AA12	PB21B	4	C	-	PB26B	4	C	-	PB30B	4	C	-
AB13	PB22A	4	T	PCLKT4_0	PB27A	4	T	PCLKT4_0	PB31A	4	T	PCLKT4_0
AA13	PB22B	4	C	PCLKC4_0	PB27B	4	C	PCLKC4_0	PB31B	4	C	PCLKC4_0
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA14	PB23A	4	T	-	PB28A	4	T	-	PB32A	4	T	-
AB14	PB23B	4	C	-	PB28B	4	C	-	PB32B	4	C	-
W12	PB24A	4	-	-	PB29A	4	-	-	PB33A	4	-	-
W13	PB25B	4	-	-	PB30B	4	-	-	PB34B	4	-	-
AA15	PB26A	4	T	DQS	PB31A	4	T	DQS	PB35A	4	T	DQS
AB15	PB26B	4	C	VREF1_4	PB31B	4	C	VREF1_4	PB35B	4	C	VREF1_4
AA16	PB27A	4	T	-	PB32A	4	T	-	PB36A	4	T	-
AB16	PB27B	4	C	-	PB32B	4	C	-	PB36B	4	C	-
Y17	PB28A	4	T	-	PB33A	4	T	-	PB37A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA17	PB28B	4	C	-	PB33B	4	C	-	PB37B	4	C	-
Y13	PB29A	4	T	-	PB34A	4	T	-	PB38A	4	T	-
Y14	PB29B	4	C	-	PB34B	4	C	-	PB38B	4	C	-
AB17	PB30A	4	T	-	PB35A	4	T	-	PB39A	4	T	-
Y18	PB30B	4	C	-	PB35B	4	C	-	PB39B	4	C	-
AA18	PB31A	4	T	VREF2_4	PB36A	4	T	VREF2_4	PB40A	4	T	VREF2_4
AB18	PB31B	4	C	-	PB36B	4	C	-	PB40B	4	C	-
Y19	PB32A	4	-	-	PB37A	4	-	-	PB41A	4	-	-
AB19	PB33B	4	-	-	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA19	PB34A	4	T	DQS	PB39A	4	T	DQS	PB43A	4	T	DQS
Y20	PB34B	4	C	-	PB39B	4	C	-	PB43B	4	C	-
W14	PB35A	4	T	-	PB40A	4	T	-	PB44A	4	T	-
W15	PB35B	4	C	-	PB40B	4	C	-	PB44B	4	C	-
AB20	PB36A	4	T	-	PB41A	4	T	-	PB45A	4	T	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L1	-	-	-	-	PL23A	7	T ³	-
M1	-	-	-	-	PL23B	7	C ³	-
M2	-	-	-	-	PL24A	7	-	-
L5	VCCP0	-	-	-	VCCP0	-	-	-
N2	GNDP0	-	-	-	GNDP0	-	-	-
N1	-	-	-	-	PL25B	6	-	-
P2	-	-	-	-	PL26A	6	T ³	-
P1	-	-	-	-	PL26B	6	C ³	-
M4	PL23A	6	T ³	-	PL27A	6	T ³	-
M3	PL23B	6	C ³	-	PL27B	6	C ³	-
R2	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
R1	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
N3	PL25A	6	T ³	-	PL29A	6	T ³	-
N4	PL25B	6	C ³	-	PL29B	6	C ³	-
M5	PL26A	6	-	-	PL30A	6	-	-
N5	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
T2	PL28A	6	T ³	DQS	PL32A	6	T ³	DQS
T1	PL28B	6	C ³	-	PL32B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U2	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
U1	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
P3	PL30A	6	T ³	-	PL34A	6	T ³	-
P4	PL30B	6	C ³	-	PL34B	6	C ³	-
P6	PL32A	6	T ³	-	PL36A	6	T ³	-
P5	PL32B	6	C ³	-	PL36B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
V2	PL33A	6	T	-	PL37A	6	T	-
V1	PL33B	6	C	-	PL37B	6	C	-
W2	PL34A	6	T ³	-	PL38A	6	T ³	-
W1	PL34B	6	C ³	-	PL38B	6	C ³	-
R3	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
R4	PL36B	6	-	-	PL40B	6	-	-
R6	PL37A	6	T ³	DQS	PL41A	6	T ³	DQS
R5	PL37B	6	C ³	-	PL41B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
Y2	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
Y1	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
T3	PL39A	6	T ³	-	PL43A	6	T ³	-
T4	PL39B	6	C ³	-	PL43B	6	C ³	-
W3	PL40A	6	T ³	-	PL44A	6	T ³	-
V3	PL40B	6	C ³	-	PL44B	6	C ³	-

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3FN388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4FN388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3FN484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4FN484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4FN484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4QN208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3TN144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4TN144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3TN100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4TN100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4FN256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3QN208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4QN208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3TN144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4TN144I	100	1.2V	-4	TQFP	144	IND	5.8K